

General Description

The WSD1216BDN22 is the highest performance trench P-Channel MOSFETs with extreme high cell density, which provide excellent $R_{DS(ON)}$ and gate charge for most of the small power switching and load switch applications.

The WSD1216BDN22 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

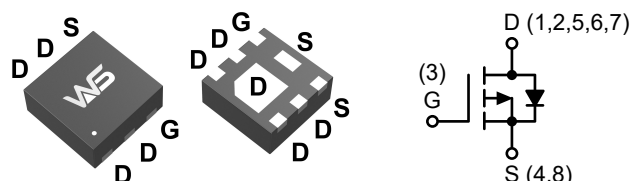
Product Summary

BVDSS	$R_{DS(ON)}$	ID
-12V	14mΩ	-15A

Applications

- High Frequency Point-of-Load Synchronous Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

DFN2X2-6S Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-12	V
V_{GS}	Gate-Source Voltage	±8	V
$I_D@T_c=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ -4.5\text{V}^1$	-15	A
$I_D@T_c=70^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ -4.5\text{V}^1$	-11	A
I_{DM}	300μS Pulsed Drain Current, $V_{GS}=-4.5\text{V}^2$	-35.5	A
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation ³	1.8	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	90	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	28	°C/W

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-12	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to 25°C , $I_D=-1\text{mA}$	---	-0.01	---	V/ $^{\circ}\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=-4.5V, I_D=-5.2A$	---	14	23	m Ω
		$V_{GS}=-2.5V, I_D=-4.2A$	---	20	35	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-0.5	-0.65	-1.0	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	3.13	---	mV/ $^{\circ}\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-8V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	---	---	-1	μA
		$V_{DS}=-8V, V_{GS}=0V, T_J=55^{\circ}\text{C}$	---	---	-5	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 8V, V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=-5V, I_D=-1A$	---	16	---	S
R_g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	2	---	Ω
Q_g	Total Gate Charge (-4.5V)	$V_{DS}=-4V, V_{GS}=-4.5V, I_D=-4.1A$	---	11.5	---	nC
Q_{gs}	Gate-Source Charge		---	1.5	---	
Q_{gd}	Gate-Drain Charge		---	3.2	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-4V, V_{GS}=-4.5V, R_G=1\Omega$ $I_D=-3.3A, R_L=1.2\Omega$	---	25	---	ns
T_r	Rise Time		---	45	---	
$T_{d(off)}$	Turn-Off Delay Time		---	72	---	
T_f	Fall Time		---	60	---	
C_{iss}	Input Capacitance	$V_{DS}=-6V, V_{GS}=0V, f=1\text{MHz}$	---	1100	---	μF
C_{oss}	Output Capacitance		---	390	---	
C_{riss}	Reverse Transfer Capacitance		---	300	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current ^{1,4}	$V_G=V_D=0V$, Force Current	---	---	-2.0	A
I_{SM}	Pulsed Source Current ^{2,4}		---	---	-12	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V, I_S=-1A, T_J=25^{\circ}\text{C}$	---	---	-1.2	V
t_{rr}	Reverse Recovery Time	$I_F=-4.1A, di/dt=100A/\mu s, T_J=25^{\circ}\text{C}$	---	20	---	nS
Q_{rr}	Reverse Recovery Charge		---	9	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper, $t \leq 10\text{sec}$.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

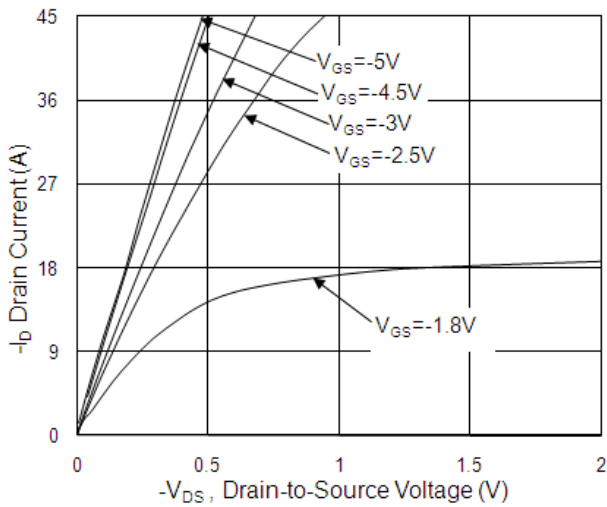


Fig.1 Typical Output Characteristics

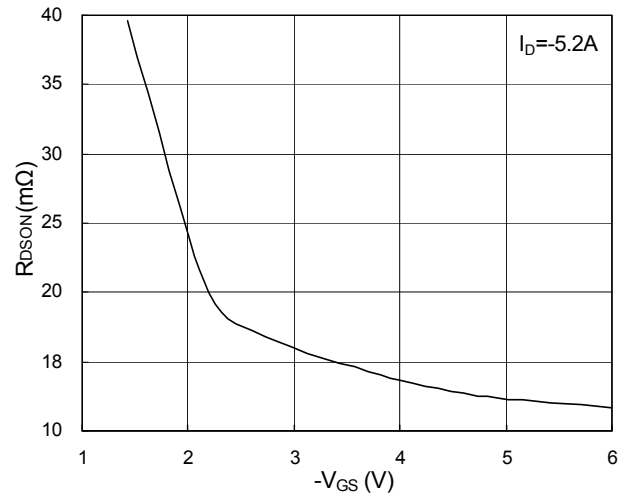


Fig.2 On-Resistance vs. Gate-Source

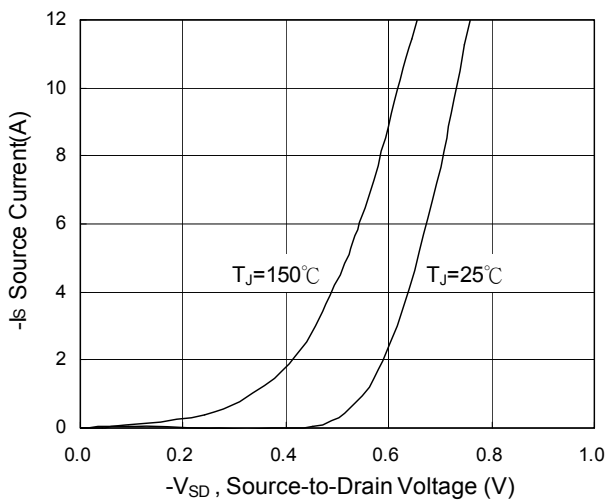


Fig.3 Forward Characteristics Of Reverse

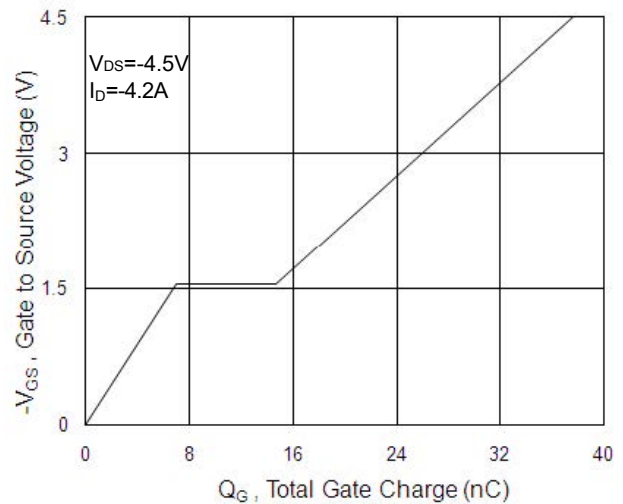


Fig.4 Gate-Charge Characteristics

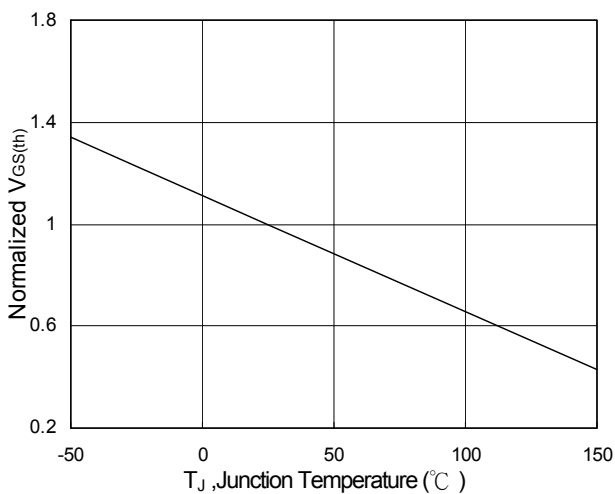


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

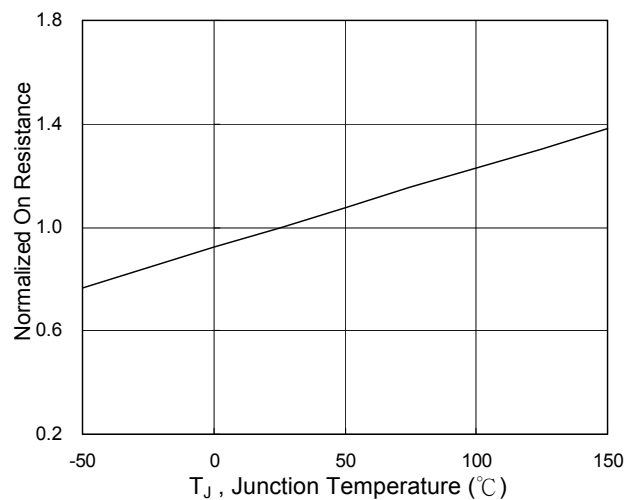


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

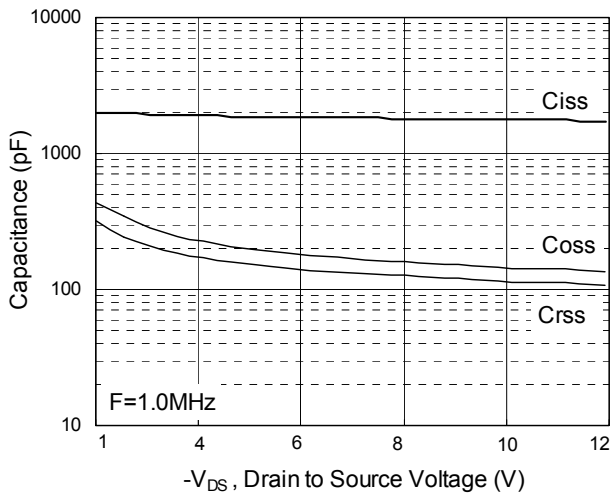


Fig.7 Capacitance

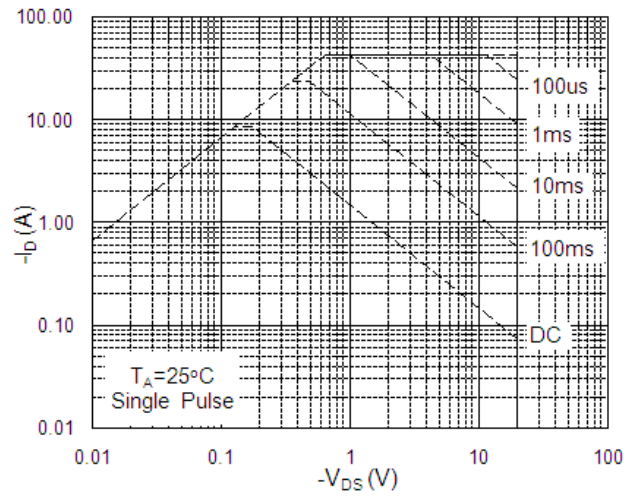


Fig.8 Safe Operating Area

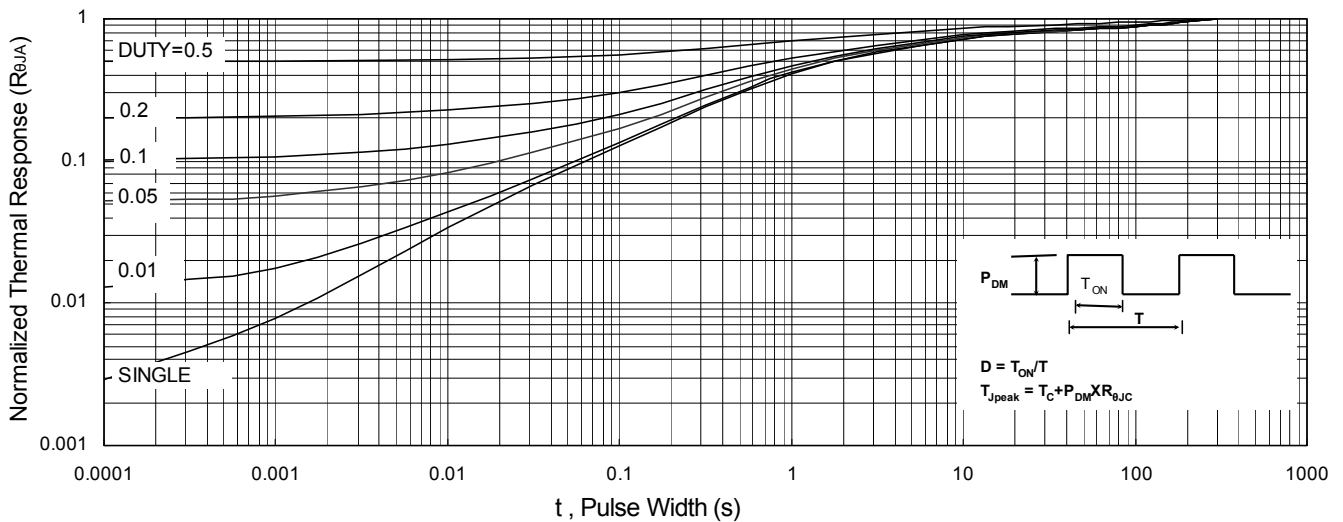


Fig.9 Normalized Maximum Transient Thermal Impedance

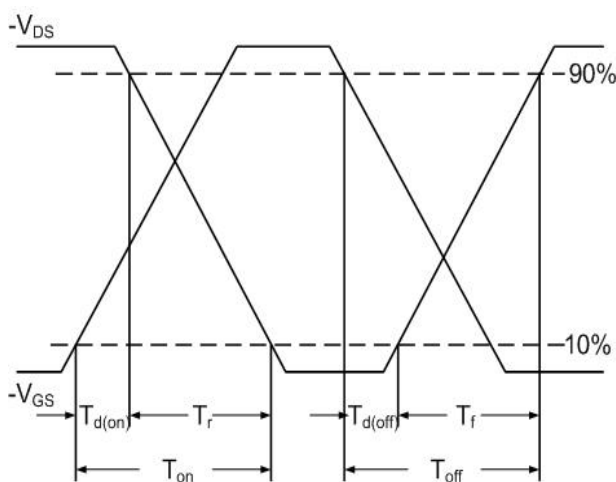


Fig.10 Switching Time Waveform

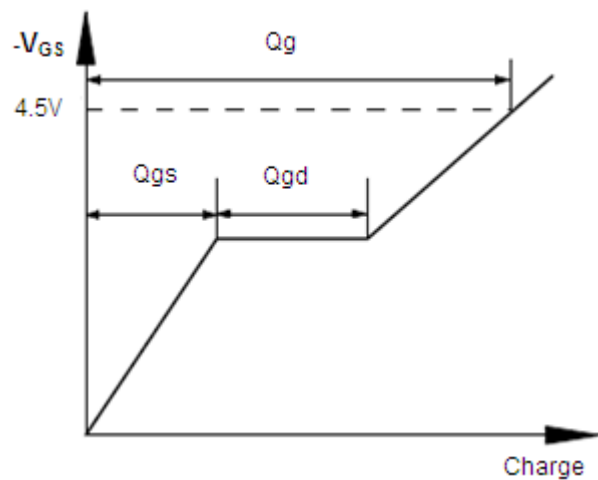
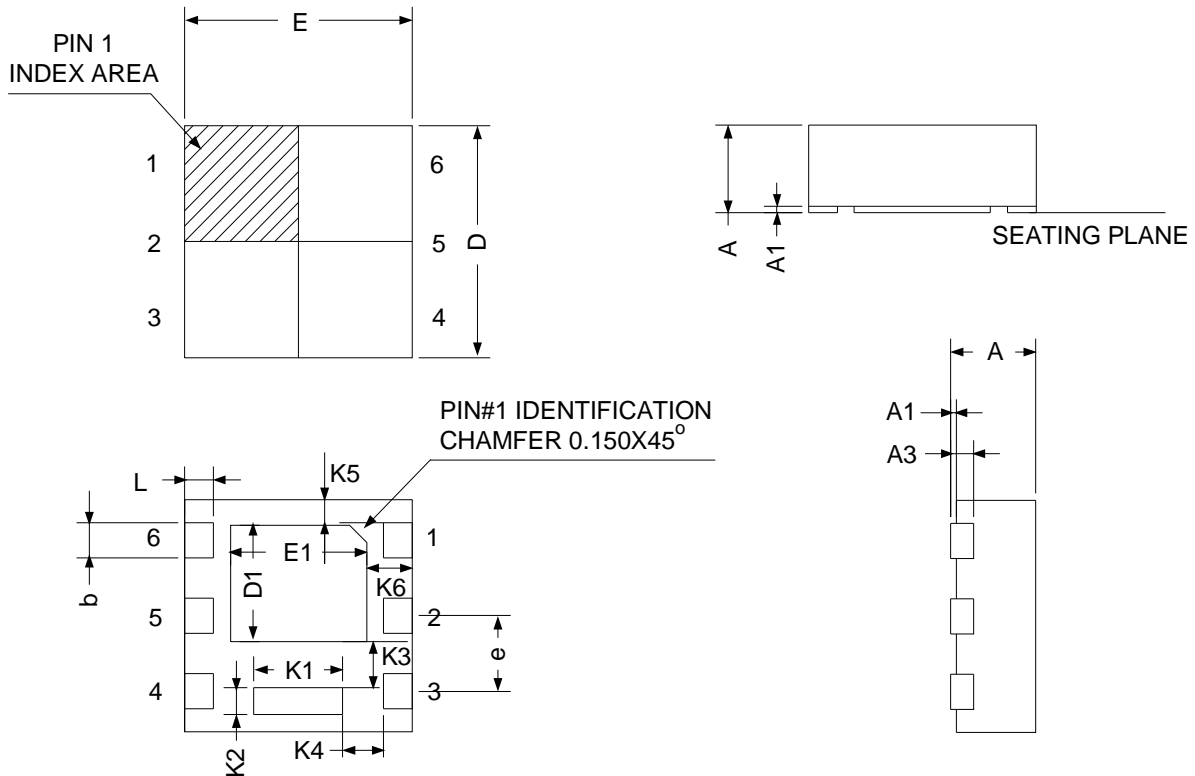


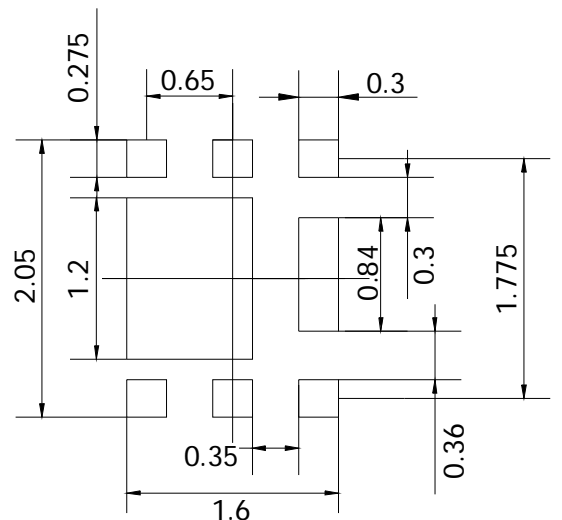
Fig.11 Gate Charge Waveform

Packaging information



SYMBOL	DFN2X2-6S			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.70	0.80	0.028	0.031
A1	0.00	0.05	0.000	0.002
A3	0.200 REF		0.008 REF	
b	0.25	0.35	0.010	0.014
D	1.90	2.10	0.075	0.083
E	1.90	2.10	0.075	0.083
D1	0.90	1.10	0.035	0.043
E1	0.90	1.10	0.035	0.043
e	0.65 BSC		0.026 BSC	
L	0.20	0.30	0.008	0.012
K1	0.65	0.85	0.026	0.033
K2	0.20	-	0.008	-
K3	0.20	-	0.008	-
K4	0.32	-	0.013	-
K5	0.20	0.26	0.008	0.010
K6	0.45	0.55	0.018	0.022

RECOMMENDED LAND PATTERN



UNIT: mm

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